

ABSTRACT

This Sheet Has Been Replaced



An automated electroplating apparatus for use in electroplating integrated circuits, including a plurality of adjacent processing cells, at least one of which being elongated and gripping means for gripping articles to be plated and at least one transporting means, comprising a plurality of transporters, for transporting the gripping means from cell to cell, and the direction of movement of the gripping means from cell to cell is transverse to the longitudinal axis of the elongated processing cell. The apparatus further includes a support means to support the gripping means at each cell. The gripping means comprises a number of pivotable gripping members, which may be arranged in a row, attached to a flight bar.